## IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently Amended) A method for processing a substrate in a processing chamber, comprising:

forming a conductive material layer on a surface of the substrate;

depositing an amorphous carbon layer on the conductive material layer <u>by a</u> method comprising:

introducing into the processing chamber one or more hydrocarbon compounds having the general formula  $C_xH_y$ , wherein x has a range of 2 to 4 and y has a range of 2 to 10; and

generating a plasma of the one or more hydrocarbon compounds by applying power from a dual-frequency RF source;

etching the amorphous carbon layer to form a patterned amorphous carbon layer; and

etching feature definitions in the conductive material layer corresponding to the patterned amorphous carbon layer.

- 2. (Original) The method of claim 1, wherein the conductive material is selected from the group of aluminum or aluminum alloy.
- 3. (Currently Amended) The method of claim [[1]] 6, wherein the depositing an amorphous carbon layer comprises:

introducing into the processing chamber one or more hydrocarbon compounds having the general formula  $C_xH_y$ , wherein x has a range of 2 to 4 and y has a range of 2 to 10; and

generating a plasma of the one or more hydrocarbon compounds the first frequency is provided at a power between 200 watts and 800 watts and the second frequency is provided at a power between about 1 watt and about 200 watts.

- 4. (Currently Amended) The method of claim [[3]]  $\underline{1}$ , wherein the one or more hydrocarbon compounds are selected from the group consisting of propylene ( $C_3H_6$ ), propyne ( $C_3H_4$ ), propane ( $C_3H_8$ ), butane ( $C_4H_{10}$ ), butylene ( $C_4H_8$ ), butadiene ( $C_4H_6$ ), acetelyne acetylene ( $C_2H_2$ ), and combinations thereof.
- 5. (Currently Amended) The method of claim [[3]] 1, further comprising introducing an inert gas with the one or more hydrocarbons into the processing chamber.
- 6. (Currently Amended) The method of claim [[3]] 1, wherein the generating a plasma comprises applying power from a dual-frequency RF source comprises providing a first frequency between about 10 MHz and about 30 MHz and a second frequency between about 100 KHz and about 500 KHz.
- 7. (Original) The method of claim 1, wherein the etch selectivity of amorphous carbon to the conductive material is between about 1:3 and about 1:10.
- 8. (Original) The method of claim 1, wherein the amorphous carbon layer comprises an anti-reflective coating.
- 9. (Currently Amended) A method for processing a substrate in a chamber, comprising:

forming a conductive material layer on a surface of the substrate;

depositing an amorphous carbon hardmask on the conductive material layer <u>by a</u> <u>method comprising:</u>

introducing into the processing chamber one or more hydrocarbon compounds having the general formula  $C_xH_y$ , wherein x has a range of 2 to 4 and y has a range of 2 to 10; and

generating a plasma of the one or more hydrocarbon compounds by applying power from a dual-frequency RF source;

depositing an anti-reflective coating on the amorphous carbon hardmask;

depositing a patterned resist material on the anti-reflective coating;

etching the anti-reflective coating and amorphous carbon hardmask to the conductive material layer; and

etching feature definitions in the conductive material layer.

- 10. (Original) The method of claim 9, wherein the conductive material is selected from the group of aluminum or aluminum alloy.
- 11. (Currently Amended) The method of claim [[9]] 14, wherein the depositing an amorphous carbon layer comprises:

introducing into the processing chamber one or more hydrocarbon compounds having the general formula  $C_xH_y$ , wherein x has a range of 2 to 4 and y has a range of 2 to 10; and

generating a plasma of the one or more hydrocarbon compounds the first frequency is provided at a power between 200 watts and 800 watts and the second frequency is provided at a power between about 1 watt and about 200 watts.

- 12. (Currently Amended) The method of claim [[11]]  $\underline{9}$ , wherein the one or more hydrocarbon compounds are selected from the group consisting of propylene ( $C_3H_6$ ), propyne ( $C_3H_4$ ), propane ( $C_3H_8$ ), butane ( $C_4H_{10}$ ), butylene ( $C_4H_8$ ), butadiene ( $C_4H_6$ ), acetelyne acetylene ( $C_2H_2$ ), and combinations thereof.
- 13. (Currently Amended) The method of claim [[11]] 9, further comprising introducing an inert gas with the one or more hydrocarbons into the processing chamber.
- 14. (Currently Amended) The method of claim [[11]] 9, wherein the generating a plasma comprises applying power from a dual-frequency RF source comprises providing a first frequency between about 10 MHz and about 30 MHz and a second frequency between about 100 KHz and about 500 KHz.

- 15. (Original) The method of claim 9, wherein the anti-reflective coating is a material selected from the group of silicon nitride, silicon carbide, carbon-doped silicon oxide, amorphous carbon, and combinations thereof.
- 16. (Currently Amended) The method of claim 9, further comprising depositing a barrier layer prior to depositing the aluminum conductive material layer.
- 17. (Currently Amended) The method of claim 9, further comprising removing the resist material prior to etching feature definitions in the aluminum conductive material layer.
- 18. (Original) The method of claim 9, wherein the etch selectivity of amorphous carbon to the conductive material is between about 1:3 and about 1:10.
- 19. (Currently Amended) A method for processing a substrate in a chamber, comprising:

forming an aluminum-containing layer on a surface of the substrate;

depositing an amorphous carbon hardmask on the aluminum-containing layer <u>by</u> a method comprising:

introducing into the processing chamber one or more hydrocarbon compounds having the general formula  $C_xH_y$ , wherein x has a range of 2 to 4 and y has a range of 2 to 10; and

generating a plasma of the one or more hydrocarbon compounds by applying power from a dual-frequency RF source;

depositing an anti-reflective coating on the amorphous carbon hardmask, wherein the anti-reflective coating is a material selected from the group of silicon nitride, silicon carbide, carbon-doped silicon oxide, amorphous carbon, and combinations thereof;

depositing a patterned resist material on the anti-reflective coating;

etching the anti-reflective coating and amorphous carbon hardmask to the aluminum-containing layer;

removing the resist material;

etching feature definitions in the aluminum-containing layer at an etch selectivity of amorphous carbon to the aluminum-containing between about 1:3 and about 1:10; and

removing the one or more amorphous carbon layers by exposing the one or more amorphous carbon layers to a plasma of a hydrogen-containing gas or an oxygen-containing gas.

- 20. (Currently Amended) The method of claim 19, wherein the one or more hydrocarbon compounds are selected from the group consisting of propylene ( $C_3H_6$ ), propyne ( $C_3H_4$ ), propane ( $C_3H_8$ ), butane ( $C_4H_{10}$ ), butylene ( $C_4H_8$ ), butadiene ( $C_4H_6$ ), acetelyne acetylene e ( $C_2H_2$ ), and combinations thereof.
- 21. (Original) The method of claim 19, further comprising introducing an inert gas with the one or more hydrocarbons into the processing chamber.
- 22. (Currently Amended) The method of claim 19, wherein the generating a plasma comprises applying power from a dual-frequency RF source comprises providing a first frequency between about 10 MHz and about 30 MHz at a power between 200 watts and 800 watts and a second frequency between about 100 KHz and about 500 KHz at a power between about 1 watt and about 200 watts.